



N-Channel Enhancement Mode Field Effect Transistor

PRODUCT SUMMARY

V _{DSS}	I _D	R _{DS(ON)} (Ω) Typ
500V	7A	1.2 @ V _{GS} =10V

FEATURES

- Super high dense cell design for low R_{DS(ON)}.
- Rugged and reliable.
- TO-220F Package.



ORDERING INFORMATION

Ordering Code	Package	Marking Code	Delivery Mode	RoHS Status
SDF07N50PT	TO-220F	07N50T	Tube	Pb Free

ABSOLUTE MAXIMUM RATINGS (T_C=25°C unless otherwise noted)

Symbol	Parameter	Limit	Units	
V _{DS}	Drain-Source Voltage	500	V	
V _{GS}	Gate-Source Voltage	±30	V	
I _D	Drain Current-Continuous ^a	T _C =25°C	7.0	A
		T _C =100°C	4.9	A
I _{DM}	-Pulsed ^a	20	A	
E _{AS}	Single Pulse Avalanche Energy ^c	225	mJ	
P _D	Maximum Power Dissipation	T _C =25°C	31	W
		T _C =100°C	16	W
T _J , T _{STG}	Operating Junction and Storage Temperature Range	-55 to 175	°C	

THERMAL CHARACTERISTICS

R _{θJC}	Thermal Resistance, Junction-to-Case	4.8	°C/W
R _{θJA}	Thermal Resistance, Junction-to-Ambient	62.5	°C/W

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ELECTRICAL CHARACTERISTICS (T_C=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
OFF CHARACTERISTICS						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250uA	500			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =400V, V _{GS} =0V			1	uA
I _{GSS}	Gate-Body Leakage Current	V _{GS} = ±30V, V _{DS} =0V			±100	nA
ON CHARACTERISTICS						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250uA	2	3	4	V
R _{DS(ON)}	Drain-Source On-State Resistance	V _{GS} =10V, I _D =3.5A		1.2	1.5	ohm
g _{FS}	Forward Transconductance	V _{DS} =20V, I _D =3.5A		4.2		S
DYNAMIC CHARACTERISTICS [°]						
C _{ISS}	Input Capacitance	V _{DS} =25V, V _{GS} =0V f=1.0MHz		581		pF
C _{OSS}	Output Capacitance			65		pF
C _{RSS}	Reverse Transfer Capacitance			9		pF
SWITCHING CHARACTERISTICS [°]						
t _{D(ON)}	Turn-On Delay Time	V _{DD} =250V I _D =1A V _{GS} =10V R _{GEN} =25 ohm		27		ns
t _r	Rise Time			17		ns
t _{D(OFF)}	Turn-Off Delay Time			34		ns
t _f	Fall Time			10		ns
Q _g	Total Gate Charge	V _{DS} =250V, I _D =1A, V _{GS} =10V		7		nC
Q _{gs}	Gate-Source Charge	V _{DS} =250V, I _D =1A, V _{GS} =10V		1.8		nC
Q _{gd}	Gate-Drain Charge			2.8		nC
DRAIN-SOURCE DIODE CHARACTERISTICS AND MAXIMUM RATINGS						
V _{SD}	Diode Forward Voltage	V _{GS} =0V, I _S =2A		0.79	1.4	V
Notes						
a. Drain current limited by maximum junction temperature.						
b. Guaranteed by design, not subject to production testing.						
c. Starting T _J =25°C, L=50mH, V _{DD} = 50V. (See Figure 12)						

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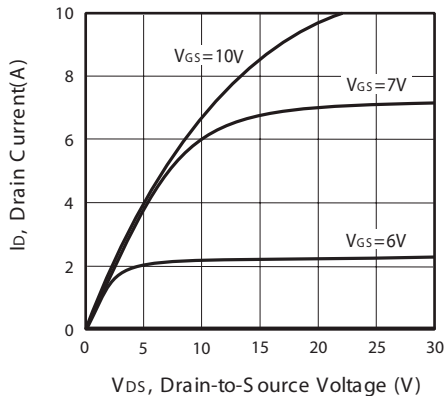


Figure 1. Output Characteristics

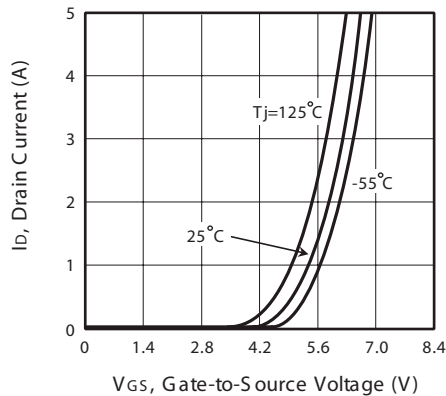


Figure 2. Transfer Characteristics

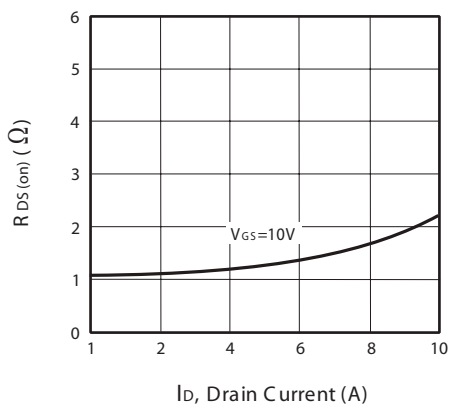


Figure 3. On-Resistance vs. Drain Current and Gate Voltage

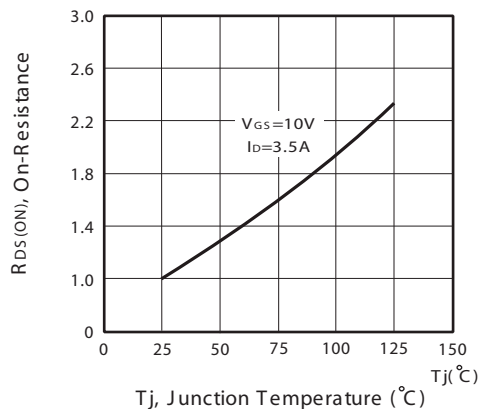


Figure 4. On-Resistance Variation with Drain Current and Temperature

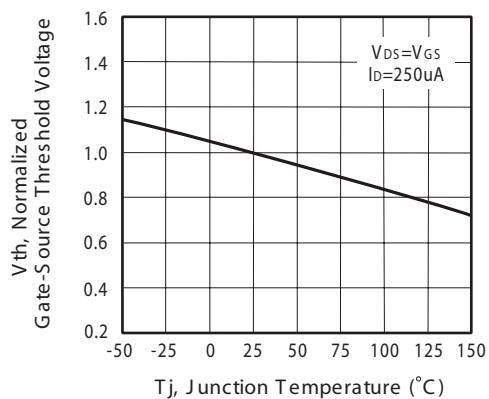


Figure 5. Gate Threshold Variation with Temperature

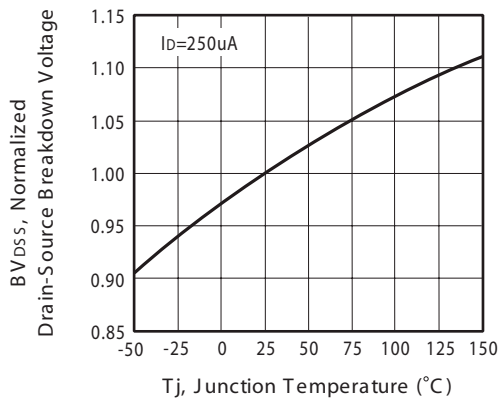


Figure 6. Breakdown Voltage Variation with Temperature

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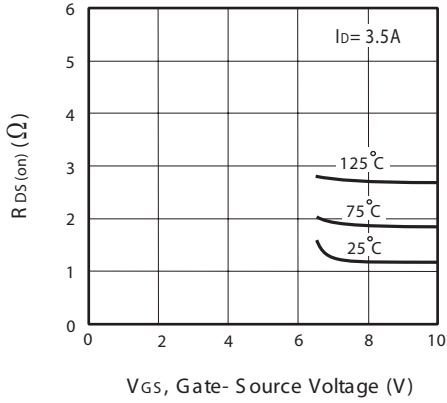


Figure 7. On-Resistance vs. Gate-Source Voltage

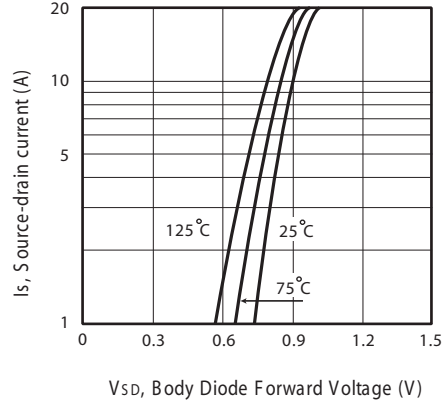


Figure 8. Body Diode Forward Voltage Variation with Source Current

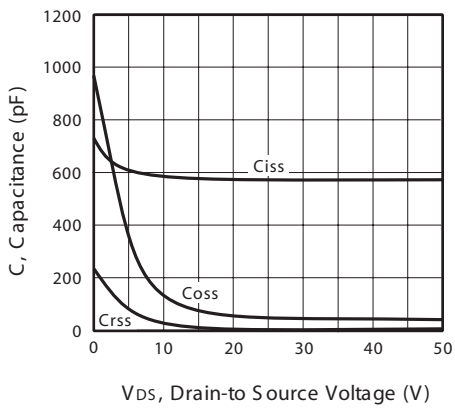


Figure 9. Capacitance

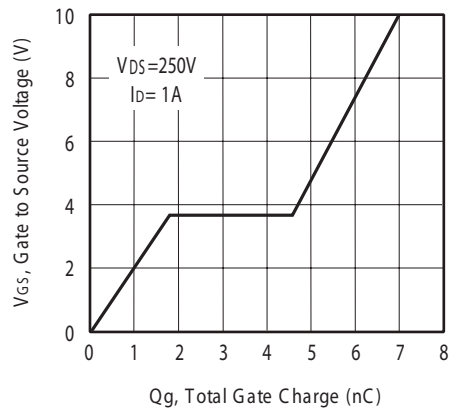


Figure 10. Gate Charge

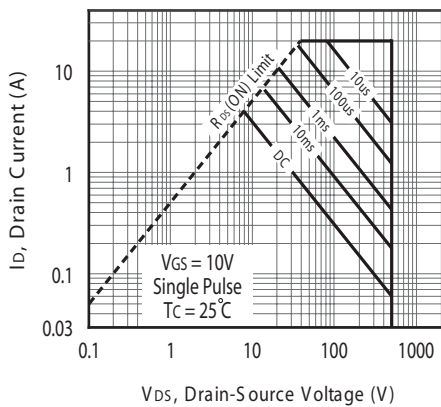
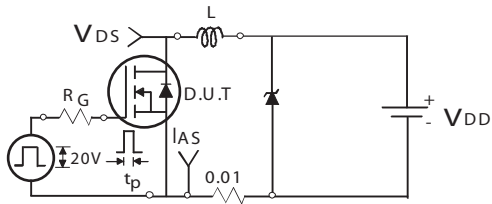


Figure 11a. Maximum Safe Operating Area for SDF07N50T

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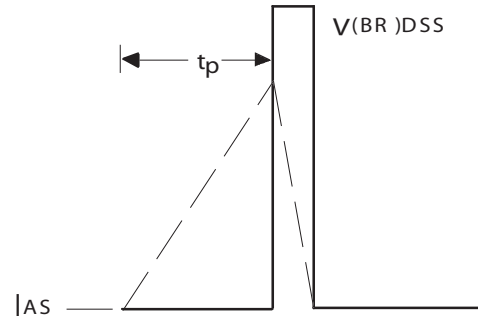
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Unclamped Inductive Test Circuit

Figure 12a.



Unclamped Inductive Waveforms

Figure 12b.

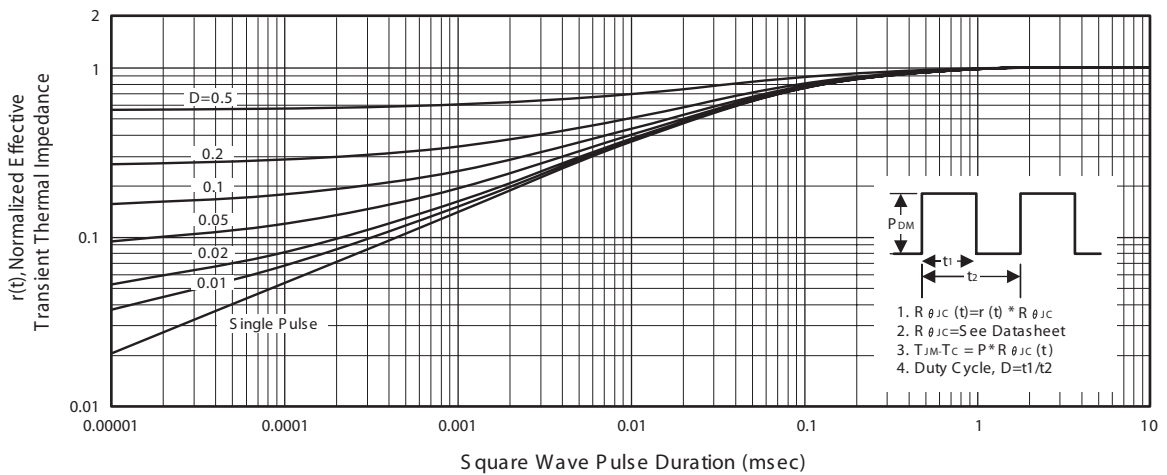


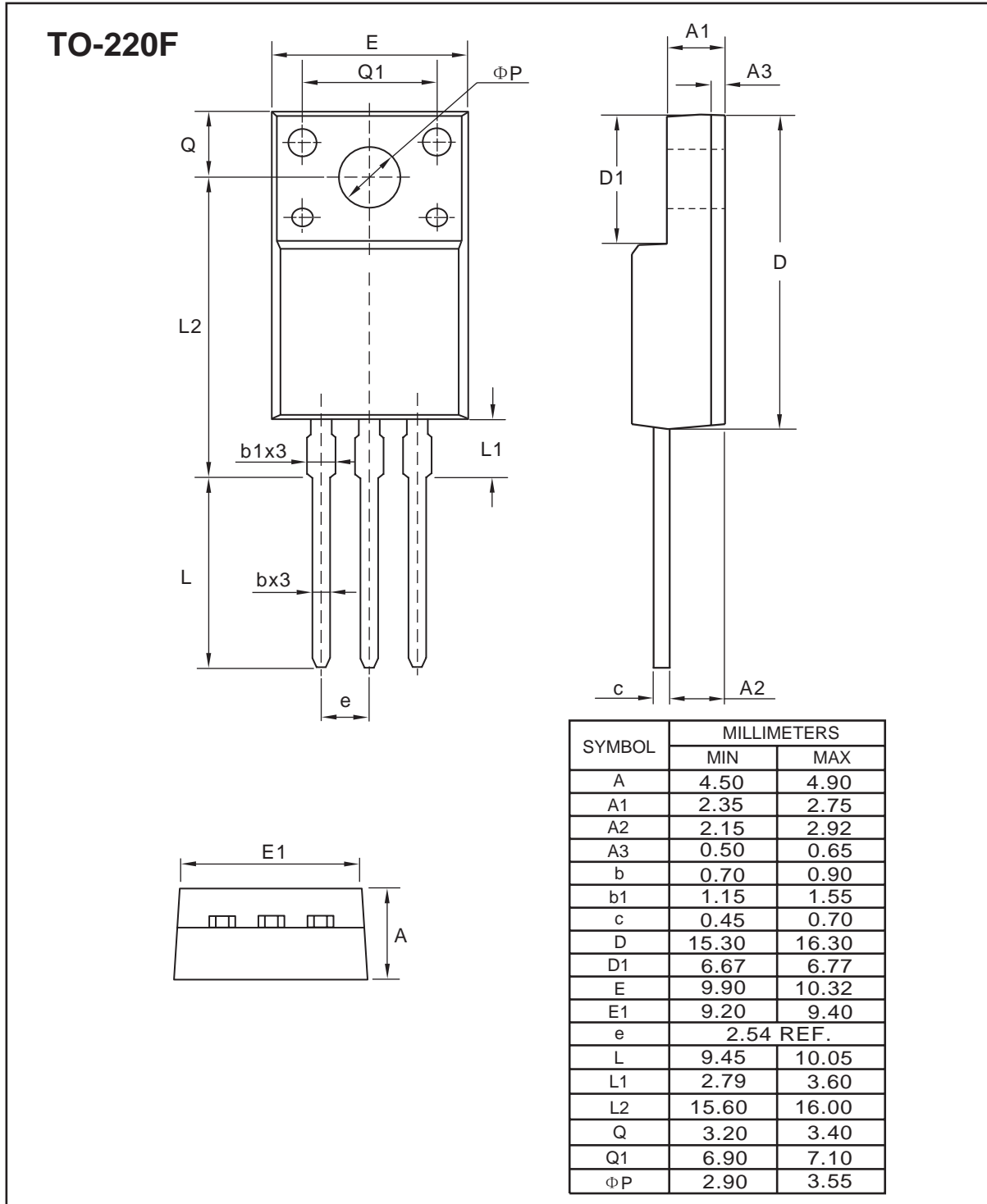
Figure 13b. Normalized Thermal Transient Impedance Curve for SDF07N50T

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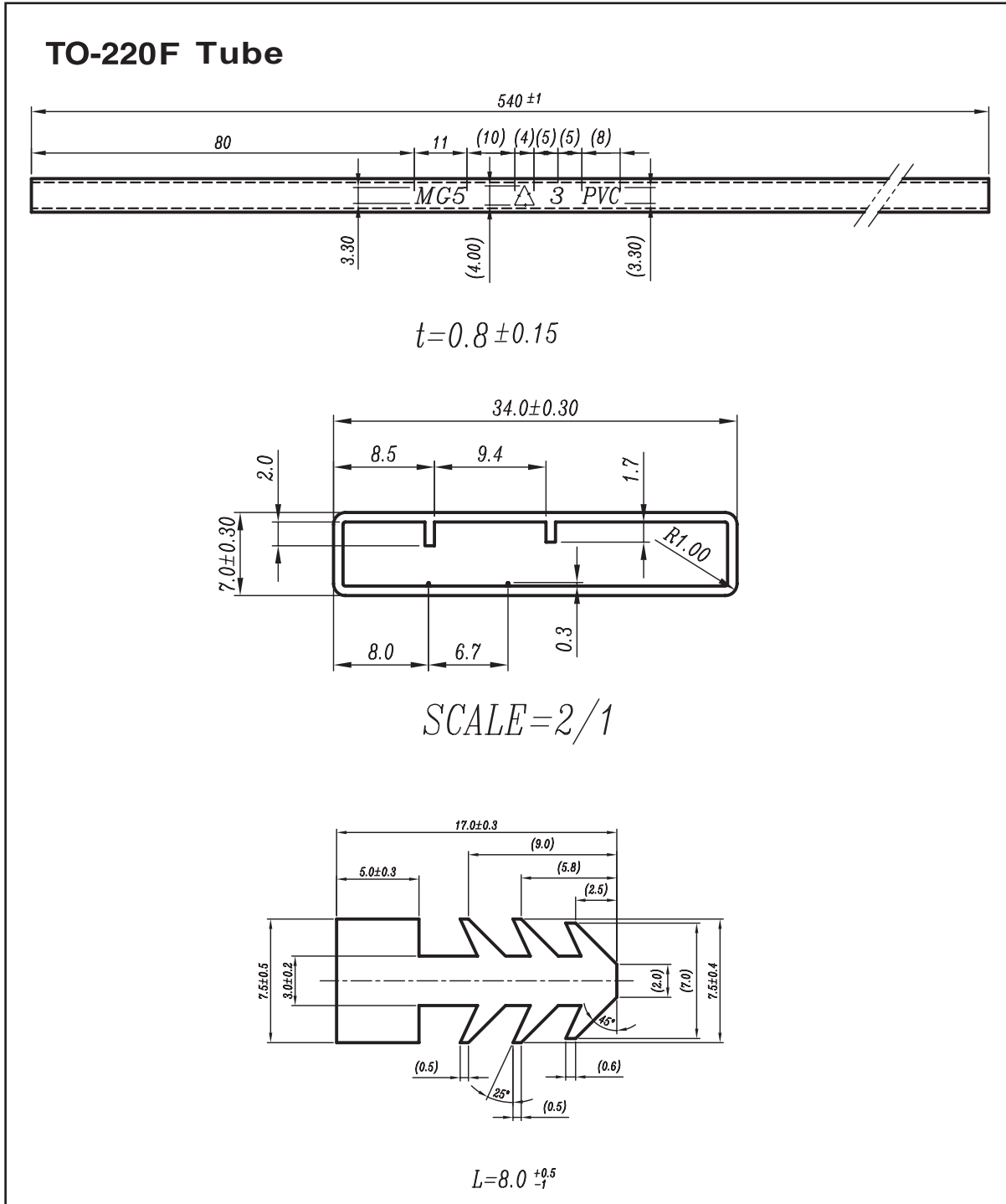
PACKAGE OUTLINE DIMENSIONS



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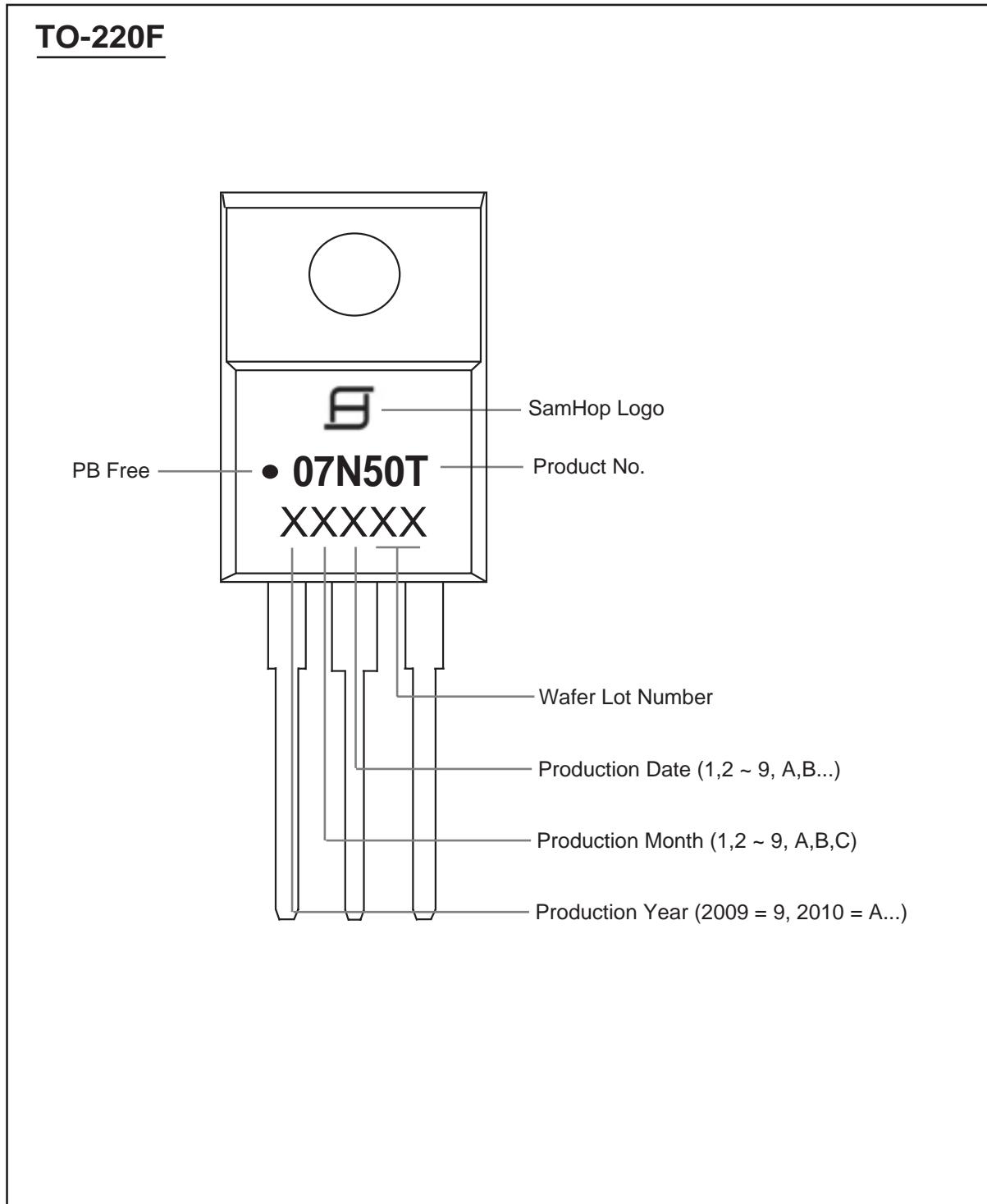


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TOP MARKING DEFINITION



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